Rochester Electronics®

Space Level S/V Flows

Devices are processed to the Class V requirements specified in MIL-PRF-38535 and SMD detailed drawings.

START

- WAFER TRACEABILITY and DESIGN VERIFICATION
- WAFER LOT ACCEPTANCE
- OUTGOING QA INSPECT
- Assembly House INCOMING QA INSPECT
- WAFER SAW and DIE PREP
- SECOND OPTICAL INSPECTION (Condition A)
- QA LOT ACCEPTANCE
- FRAME ATTACH
- DIE ATTACH
- DIE ATTACH CURE
- WIRE BOND
- NON-DESTRUCT BOND PULL
- THIRD OPTICAL INSPECTION
- QA LOT ACCEPTANCE Rochester FIELD SOURCE SURVEILLANCE LOT ACCEPTANCE (optional)
- PRE-SEAL BAKE and VACUUM PRE-WELD BAKE (TO type package only)
- HERMETIC SEAL / WELD
- TEMPERATURE CYCLING
- CONSTANT ACCELERATION
- PARTICAL NOISE DETECTION (PIND)
- LEAD TRIM (if applicable)
- SOLDER DIP LEAD FINISH and INSPECTION
- MARK and CURE (optional sequence)
- SERIALIZATION
- RADIOGRAPHY (X-RAY)
- FINE LEAK SEAL TEST
- GROSS LEAK SEAL TEST
- VISUAL and PACKAGE LOAD
- QA LOT ACCEPTANCE
- SHIP
- INCOMING QA LOT ACCEPTANCE
- Test Lab INCOMING INSPECT
- INITIAL ELECTRICAL TEST
- BURN IN (240 HRS at 125° C Minimum)
- SURVEILLANCE LOT ACCEPTANCE (Optional)
- ELECTRICAL TEST INTERIM and FINAL
- QUALITY CONFORMANCE INSPECTION Group A
- FINE/GROSS LEAK
- EXTERNAL VISUAL
- QUALITY CONFORMANCE INSPECTION Groups B, C, and D
- FINAL QA LOT ACCEPTANCE

FINISH

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